5 Specifications

5.1 Absolute Maximum Ratings (1)

Table 5-1 Absolute Maximum Ratings

SYMBOL	DESCRIPTION	MIN	MAX	UNIT
VIN1/VIN2/VIN3	Input Voltage	-0.3	7	V
Ta	Operating Temperature Range	-40	85	°C
TJ	Junction Temperature Range	-40	125	°C
Ts	Storage Temperature Range	-40	150	°C
TLEAD	Maximum Soldering Temperature (at leads, 10sec)		300	°C

(1)Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

5.2 ESD Ratings

Table 5-2 ESD Ratings

		VALUE	UNIT
VESD	Human body model(HBM)(1)	±2000	V
	Charged device model(CDM)(2)	±750	V

(1) Reference: ESDA/JEDEC JS-001-2017.

(2) Reference: JEDEC EIA/JESD22-C101F.

5.3 Recommended Operating Conditions

Table 5-3 Recommended Operating Conditions

SYMBOL	DESCRIPTION	MIN	MAX	UNIT
VIN	Input voltage	3.0	5.5	V

5.4 Thermal Information

Table 5-4 Thermal Information

Thermal Metric(1)		VALUE	UNIT
θJA	Junction-to-ambient thermal resistance	32.6	°C/W
θJB	Junction-to-board thermal resistance	6.82	
θJC	Junction-to-case(top) thermal resistance	12.32	

(1)Thermal metrics are calculated refer to JEDEC document JESD51. The values are based on simulation.

5.5 Electrical Characteristics

V_{IN} =5V, T_A=25°C

Table 5-5 Electrical Characteristics

SYMBOL	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
PMIC Under Voltage						